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STATE OF INDIANA
OFFICE OF THE GOVERNOR
State House, Second Floor
Indianapolis, Indiana 46204

Eric J. Holcomb
Governor

October 16, 2023

Dear President Chiang:

Congratulations on the launch of this important new institute! Advanced packaging is increasingly becoming a product differentiator and is critical to defense electronics – a major activity in Indiana due to the presence of NSWC Crane. Only 3% of global packaging production is done in the U.S., but with the CHIPS for America program ramping up, we have an opportunity to bring much more of this production back to the U.S. and to Indiana where it will create high-paying jobs for Hoosiers.

ASIP will draw on the strengths of Purdue to accelerate microelectronic system integration and technology development while producing the high-tech workforce needed. Strong partnerships with companies, research organizations, and other universities will help establish Indiana as a major center of innovation in this critical technology. We look forward to working with ASIP to bring national and international microelectronics companies to Indiana.

I am deeply appreciative of Purdue University’s support for Indiana’s leadership in semiconductors.

Boiler Up!

Eric Holcomb

Eric Holcomb
Governor